

Reutlingen wafer fab

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- ▶ Areas of operation Manufacturing for semiconductors (Frontend)
Test center for semiconductors (Backend)

- ▶ Associates about 4,000

- ▶ Cleanroom surface area 35,000 m², till end of 2025: 44,000 m²

- ▶ Production facilities 150-millimeter technology since 1995
200-millimeter technology since 2010
Pre- and final measurement for 150- and 200-millimeter wafers

- ▶ Manufactured products Application-specific integrated circuits (ASICs),
low-voltage/high-voltage power semiconductors,
microelectromechanical systems (MEMS)

- ▶ Manufacturing technology 150- and 200-millimeter silicon substrates with
structural widths (nodes) of up to 180 nanometer

150-millimeter silicon carbide substrates with
structural widths (nodes) of up to 400 nanometer

- ▶ Fields of application for semiconductors Power units for electromobility, e-bikes, power
tools and further Bosch products

Automotive electronics: airbag and driver
assistance systems, Electronic Stability Control
ESC, electronic control units for electric motors
and IC engines as well as for transmissions,
parking assistants and night vision enhancement
systems

Consumer electronics: games consoles, hearables, laptops, smartphones, wearables

Investments and extension course of action

- ▶ Rising demand
Consistent development of the manufacturing capacity to meet the growing demand of semi-conductors chips (ASICs, MEMS and power semiconductors).

- ▶ From 2021 to 2023
With 150 million euros in two steps from 2021 to 2023 will gain about 4,000m² of new cleanroom surface area that will be realized in existing buildings. In addition, 150 new jobs in the fields of semiconductor development will be raised.

- ▶ Till end of 2025
State-of-the-art manufacturing: more than 250 million euros will be invested for a new element, the total amount of the cleanroom surface area will raise up to 44,000 m².